PRESS RELEASE

FOR IMMEDIATE RELEASE

NIDEC MACHINE TOOL AMERICA Expands Advanced Manufacturing Portfolio

Wixom, MI - 12 MAR 2026 – NIDEC MACHINE TOOL AMERICA has announced the rebranding of its Additive Manufacturing division to Advanced Manufacturing Technologies, marking a significant step forward in the company's commitment to delivering precision manufacturing solutions across North America.

The newly named division brings three distinct technology platforms under one umbrella: LAMDA, the company's metal additive manufacturing system; ABLASER, a high-precision laser micromachining system; and BOND MEISTER, a room-temperature wafer bonding machine built for semiconductor and MEMS applications.

“This expansion reflects where the industry is heading and where we stand as a company,” said Tyson Gregory, Advanced Manufacturing Technologies Sales Manager. “By bringing these specialized systems together, we are making it easier for our North American customers to leverage our full suite of solutions.”

About the Technologies

LAMDA – DED AM System

LAMDA is NIDEC’s Laser Powder DED Additive Manufacturing system, built for large-scale metal 3D printing. The series, comprising the LAMDA200, LAMDA500, LAMDA2000, and LAMDA5000, features advanced process control with AI anomaly detection for real-time monitoring and feedback, ensuring stability and repeatability throughout the build. Additionally, its local shield nozzle allows for the printing of reactive materials without a full inert gas enclosure, which simplifies setup and speeds up delivery.

ABLASER – Laser Micromachining System

The ABLASER is built around proprietary optical head technology and a prism rotator. This enables ultra-high precision helical machining, drilling micro-holes down to ∅27 μm in materials like silicon, SiC, and ceramics with no thermal distortion. Its flexible taper hole control supports straight, forward taper, reverse taper, and hand-drum-shaped geometries.

BOND MEISTER – Room Temperature Wafer Bonding Machine

BOND MEISTER joins wafers through surface activation bonding inside a high-vacuum environment; no heat is required. This eliminates thermal stress and distortion, allowing for the bonding of dissimilar materials like GaN, GaAs, and silicon. The lineup includes the MWB-04/06-R for research, prototyping, and small to medium volume production; MWB-04/06/08-AX for high-throughput production with fully automated

cassette-to-cassette operation; and MWB-08/12-ST for 300 mm wafer bonding in high-volume applications.

Availability

All three systems are available through NIDEC MACHINE TOOL AMERICA and backed by the North American sales and service network.

###

About NIDEC MACHINE TOOL AMERICA

NIDEC MACHINE TOOL AMERICA delivers cutting-edge gear-making machines, unparalleled expertise, and end-to-end support to elevate manufacturing capabilities while maximizing efficiency and precision.

Contact:

Tyson Gregory
Advanced Manufacturing Technologies Sales Manager
248-762-4084
tyson.gregory@nidec.com

Samantha Hambleton
Marketing Coordinator
248-492-1912
samantha.hambleton@nidec.com